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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office
Atty. Docket No. 1017-003

To the Commissioner for Patents: Please re



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copy thereof.

1. Name of conveying party(ies):
Takayuki Nakamoto

Additional name(s) of conveying party(ies) attached? Yes No

102723975

s of receiving party(ies):

Name: Iwata Denko Co., Ltd.

Internal Address:

3. Nature of conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: 11/25/03

Street Address: 32-2, Minami-Senzoku 3-chome
Ota-ku

City: Tokyo State: Zip: 145-0063

Country: JAPAN

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or registration numbers(s):
If this document is being filed together with a new application, the execution date of the application is: 11/25/03

A. Patent Application No.(s)
B. Patent No.(s)

10479482

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Benjamin S. Withrow
WITHROW & TERRANOVA, P.L.L.C.
P.O. Box 1287
Cary, NC 27512

6. Total number of applications and patents involved:1

7. Total fee (37 CFR 3.41): \$40.00
 Enclosed
 Authorized to be charged to deposit account

8. Deposit account number:
50-1732
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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Benjamin S. Withrow
Name of Person Signing

Signature

December 1, 2003
Date

Total number of pages including cover sheet, attachments, and document: 4

Mail documents to be recorded with required cover sheet information to:
Director of the United States Patent and Trademark Office
PO Box 1450, Alexandria, Virginia 22313-1450

PATENT
REEL: 015208 FRAME: 0704

ASSIGNMENT

This Assignment made by me, **Takayuki Nakamoto**, hereinafter referred to as assignor, a citizen of Japan, whose post office address is c/o IWATA DENKO., LTD., 32-2, Minami-Senzoku 3-chome, Ota-ku, Tokyo, Japan

WITNESSETH: That,

WHEREAS, I am the sole inventor of certain new and useful improvements in **REMOVAL AND INSTALLATION DEVICE FOR EXTERNAL AND INTERNAL SNAP RINGS**, for which I have filed International application no. PCT/JP01/04807 on 7 June 2001 and herewith file a national phase application for grant of U.S. letters patent; and

WHEREAS, IWATA DENKO., LTD., a corporation duly organized and existing under the laws of Japan and having a principal place of business at 32-2, Minami-Senzoku 3-chome, Ota-ku, Tokyo, Japan, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in the specification executed by me concurrently herewith, and any and all Letters Patent which shall be granted therefor;

NOW, THEREFORE, To All Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the said assignor, have sold, assigned, transferred and set over unto the said assignee, its successors and assigns, the entire right, title and interest in and to the above-mentioned application and invention and in and to any and all Letters Patent of the United States which may hereafter be granted therefor, and in any and to any and all continuations, continuations-in-part, substitutions, divisions or reissues of said Letters Patent, the same to be held and enjoyed by the said assignee, for its interest, and for its own use and behalf, and the use and behalf of its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and

entirely as the same would have been held and enjoyed by me had this assignment and sale not been made.

And for the consideration aforesaid, I hereby covenant and agree to and with the said assignee, its successors and assigns, that at the time of the execution and delivery of these presents I am the sole and lawful owner of the entire right, title and interest in and to the invention, application and Letters Patent above-mentioned and that the same are unencumbered, and that I have good right and lawful authority to sell and convey the same in the manner herein set forth.


And for the consideration aforesaid, I hereby covenant and agree to and with the said assignee, its successors and assigns, that I will, whenever its counsel or the counsel of its successors and assigns, learned in the law, shall advise that an amendment, division, continuation, continuation-in-part, or substitution of, or any other proceeding in connection with said application, including interference proceedings, is lawful and desirable, sign all papers and drawings, take all rightful oaths, and do all acts necessary or required to be done for the procurement of valid Letters Patent for said invention, or for the reissue of the same without charge to my said assignee, its successors or assigns, but at its or their expense.

I hereby request the Commissioner for Patents to issue the Letters Patent in accordance with this instrument.

For the consideration aforesaid, I have sold, assigned, transferred and set over, and by these presents do sell, assign, transfer and set over, unto the said assignee, its successors, assigns or nominee, the entire right, title and interest in and to any and all Letters Patent for said invention which may be granted in countries foreign to the United States and in and to any applications for Letters Patent which may be filed for said invention in countries foreign to the

United States and in and to the invention described in said application; and I hereby authorize and empower the said assignee, its successors, assigns or nominees to apply for Letters Patent or other form of protection on said invention in its own name or in the name of its successor, assignee, or nominee, in any and all countries where it may desire to file such application and where said application may be filed by another than the inventor; and I hereby covenant and agree to sign all papers and drawings, take all rightful oaths, and do all acts necessary or required to be done for procurement of Letters Patent, or other form of protection, for said invention or inventions in countries foreign to the United States, and for further investing or confirming the right and title therein to the assignee, its successors, assignee, or nominee, without charge to my said assignee, its successor, assignee or nominee, but at its or their own expense.

IN WITNESS WHEREOF, I have hereunto set my hand and seal this the 25th day of November, 2003.



Takayuki Nakamoto